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# United States Patent [19]

Chiu et al.

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[54]	MESH STRUCTURE TO AVOID THERMAL
	GREASE PUMP-OUT IN INTEGRATED
	CIRCUIT HEAT SINK ATTACHMENTS

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[56]

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[57]

## ABSTRACT

An embodiment of the invention includes an integrated circuit package having a substrate, an integrated circuit mounted to the substrate, a thermal element, and a heat pipe disposed between the integrated circuit and the thermal element. The heat pipe includes a retaining structure impregnated with a thermal grease. The heat pipe is a result of a process that includes the step of impregnating the retaining structure with a thermal grease prior to disposing the heat pipe between the integrated circuit and the thermal element.

## 11 Claims, I Drawing Sheet



